

SEMICONDUCTOR STRUCTURE AND MANUFACTURING METHOD THEREOF, MEMORY CHIP AND ELECTRONIC DEVICE

ABSTRACT

Embodiments of the disclosure relate to the field of semiconductors and provide a semiconductor structure and a manufacturing method thereof, a memory chip and an electronic device. The semiconductor structure comprises a substrate, wherein the substrate is provided with a stacked structure, the stacked structure comprising a plurality of memory cell groups arranged in a first direction, each of the memory cell groups comprising multiple layers of memory cells arranged in a second direction, the stacked structure further comprising a plurality of horizontal signal lines arranged in the second direction, wherein each of the horizontal signal lines is in contact with one layer of the memory cells; and a plurality of leading wire posts arranged in the first direction, wherein the plurality of leading wire posts and the plurality of horizontal signal lines are arranged along a third direction, and the leading wire posts are connected to the horizontal signal lines. The embodiments of the disclosure can at least improve the integration level of the semiconductor structure.

[Fig. 4]